

SPEC. NO.: PS - 50110-XXXXX-XXX

REVISION: B

PRODUCT NAME: 0.8mm PITCH BOARD TO BOARD CONN

50110-XXXXX-XXX; 50109-XXXXX-XXX; 50112-XXXXX-XXX;

PRODUCT NO: 50119-XXXXX-XXX ; 50127-XXXXX-XXX; 50189-XXXXX-XXX

PREPARED: FENGXIAO DATE: 2014/01/18	CHECKED: DAVID DATE: 2014/01/18	APPROVED: SIMON DATE: 2014/01/18
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Aces P/N: **50110 series**

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1 Revision History

Rev.	ECN #	Revision Description	Prepared	Date
O	ECN-0812153	NEW DRAWING	KEEN	2008/12/15
A	ECN-1007052	ADD 50189-XXXXX-XXX	LIZHAO	2010/7/30
B	ECN-1401248	UPDATE WORKING VOLTAGE	FENGXIAO	2014/01/18

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2 SCOPE

This specification covers performance, tests and quality requirements for **0.8mm pitch Board To Board CONN. Including these product series as belows: 50110 series, 50127 series, 50119 series, 50112 series.50109 series. 50189 series.**

3 APPLICABLE DOCUMENTS

EIA-364 ELECTRONICS INDUSTRIES ASSOCIATION

4 REQUIREMENTS

4.1 Design and Construction

Product shall be of design, construction and physical dimensions specified on applicable product drawing.

4.2 Materials and Finish

4.2.1 Contact: High performance copper alloy (Phosphor Bronze)

- Finish:
- (a) Contact Area: [Refer to the drawing.](#)
 - (b) Under plate: [Refer to the drawing.](#)
 - (c) Solder area: [Refer to the drawing.](#)

4.2.2 Housing: Thermoplastic or Thermoplastic High Temp., UL94V-0

4.3 Ratings

4.3.1 Working Voltage Less than **36 Volts AC (per pin)**

4.3.2 Voltage: **100 Volts AC (per pin)**

4.3.3 Current: **0.5 Amperes (per pin)**

4.3.4 Operating Temperature : **-40°C to +85°C**

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5.1. Test Requirements and Procedures Summary

Item	Requirement	Standard
Examination of Product	Product shall meet requirements of applicable product drawing and specification.	Visual, dimensional and functional per applicable quality inspection plan.
ELECTRICAL		
Item	Requirement	Standard
Low-signal Level Contact Resistance	55 m Ω Max.(initial)per contact ΔR 10 m Ω Max.	Mate connectors, measure by dry circuit, 20mV Max., 100mA Max. (EIA-364-23)
Insulation Resistance	500 M Ω Min.	Unmated connectors, apply 500 V DC between adjacent terminals. (EIA-364-21)
Dielectric Withstanding Voltage	No discharge, flashover or breakdown. Current leakage: 1 mA max.	300 VAC Min. at sea level for 1 minute. Test between adjacent contacts of unmated connectors. (EIA-364-20)
MECHANICAL		
Durability	30 cycles.	The sample should be mounted in the tester and fully mated and unmated the number of cycles specified at the rate of 25.4 \pm 3mm/min. (EIA-364-09)
Mating / Unmating Forces	Mating Force:100gf Max./CKT Unmating Force:12gf Min./CKT	25.4 \pm 3 mm/minute.. Measure the force required to mate/Unmate connector. (EIA-364-13)
Terminal / Housing Retention Force	0.4 Kgf Min.	Apply axial pull out force at the speed rate of 25.4 \pm 3 mm/minute. On the terminal assembled in the housing.
Fitting Nail / Housing Retention Force	0.15Kgf Min.	Apply axial pull out force on the terminal assembled in the housing at a rate of 25 \pm 3 mm/min.
Vibration	1 μ s Max.	The electrical load condition shall be 100 mA maximum for all contacts. Subject to a simple harmonic motion having amplitude of 0.76mm (1.52mm maximum total excursion) in frequency between the limits of 10 and 55 Hz. The entire frequency range, from 10 to 55 Hz and return to 10 Hz, shall be traversed in approximately 1 minute. This motion shall be applied for 2

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		hours in each of three mutually perpendicular directions. (EIA-364-28 Condition I)
MECHANICAL		
Item	Requirement	Standard
Shock (Mechanical)	1 μ s Max.	Subject mated connectors to 50 G's (peak value) half-sine shock pulses of 11 milliseconds duration. Three shocks in each direction shall be applied along the three mutually perpendicular axes of the test specimen (18 shocks). The electrical load condition shall be 100mA maximum for all contacts. (EIA-364-27, test condition A)
ENVIRONMENTAL		
Resistance to Reflow Soldering Heat	See Product Qualification and Test Sequence Group 9 (Lead Free)	Pre Heat : 150°C~180°C, 60~120sec. Heat : 230°C Min., 40sec Min. Peak Temp. : 260°C Max, 10sec Max. Reflow number cycle: 2 times
Thermal Shock	See Product Qualification and Test Sequence Group 4	Mate module and subject to follow condition for 5 cycles. 1 cycles: -55 +0/-3 °C, 30 minutes +85 +3/-0 °C, 30 minutes (EIA-364-32, test condition A)
Humidity	See Product Qualification and Test Sequence Group 4	Mated Connector 25~65°C, 90~95% RH, 10 Cycles Reefer to Method IV. (EIA-364-31, Test condition A)
Temperature life	See Product Qualification and Test Sequence Group 5	Subject mated connectors to temperature life at 85°C for 96 hours . Measure Signal. (EIA-364-17, Test condition A)
Salt Spray (Only For Gold Plating)	See Product Qualification and Test Sequence Group 6	Subject mated/unmated connectors to 5% salt-solution concentration, 35°C (I) Gold flash for 8 hours (II) Gold plating 5 μ" for 96 hours. (EIA-364-26)
Solder ability	Tin plating: Solder able area shall have minimum of 95% solder coverage. Gold plating: Solder able area shall have	Subject the test area of contacts into the flux for 5-10 sec. And then into solder bath, Temperature at 245 \pm5°C , for 4-5 sec. (EIA-364-52)

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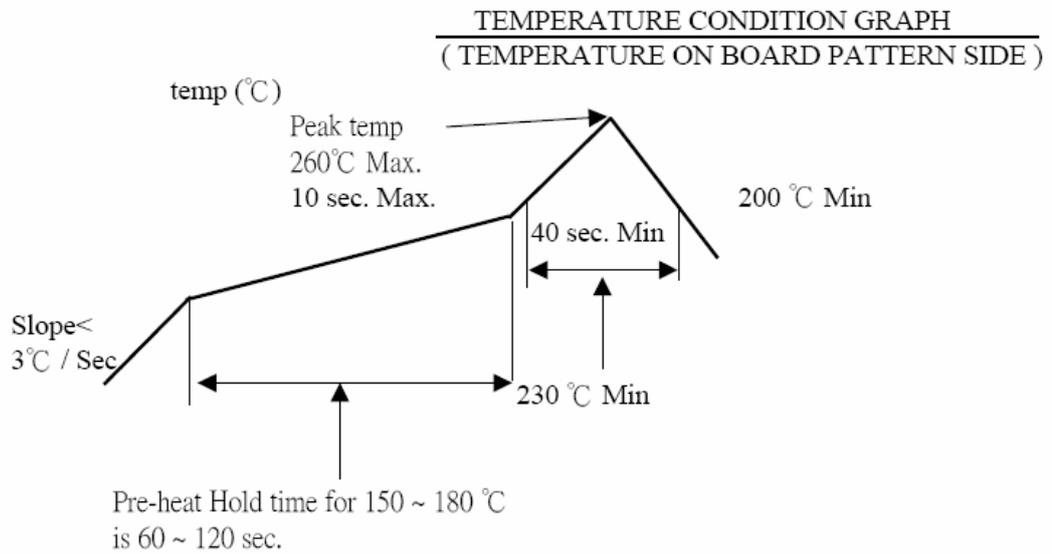
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	minimum of 75% solder coverage	
Hand Soldering Temperature Resistance	Appearance: No damage	$T \geq 350^{\circ}\text{C}$, 3sec at least.

Note. Flowing Mixed Gas shall be conducted by customer request.

6 INFRARED REFLOW CONDITION

6.1. Lead-free Process



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Test or Examination	Test Group									
	1	2	3	4	5	6	7	8	9	10
	Test Sequence									
Examination of Product				1、7	1、6	1、4			1	1
Low-signal Level Contact Resistance		1、5	1、4	2、10	2、9	2、5			3	
Insulation Resistance				3、9	3、8					
Dielectric Withstanding Voltage				4、8	4、7					
Temperature rise	1									
Mating / Unmating Forces		2、4								
Durability		3								
Vibration			2							
Shock (Mechanical)			3							
Thermal Shock				5						
Humidity				6						
Temperature life					5					
Salt Spray(Only For Gold Plating)						3				
Solder ability							1			
Terminal / Housing Retention Force								1		
Fitting Nail /Housing Retention Force								2		
Resistance to Soldering Heat									2	
Hand Soldering Temperature Resistance										2
Sample Size	2	4	4	4	4	4	2	4	4	4